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Applicant Number	09/854539
Filing Date	May 14, 2001
First Named Inventor	Intel Corporation, .
Group Art Unit	2814
Examiner Name	Peralta, Ginette

Sheet 1 of 2
Attorney Docket No: 884.415US1

US PATENT DOCUMENTS						
Examiner Initial *	USP Document Number	Publication Date	Name of Patentee or Applicant of cited Document	Class	Subclass	Filing Date If Appropriate
JP	US-2001/0013654-A1	08/16/2001	Kalidas, N., et al.	257	738	12/22/1999
JP	US-2002/0008314-A1	01/24/2002	Takeuchi, Y.	257	697	04/13/2000
JP	US-5,105,257	04/14/1992	Michii, K.	357	70	02/04/1991
JP	US-5,608,262	03/04/1997	Degani, Y., et al.	257	723	02/24/1995
JP	US-5,701,032	12/23/1997	Fischer, P. J., et al.	257	692	11/02/1995
JP	US-5,864,470	01/26/1999	Shim, I. K., et al.	361	777	06/25/1997
JP	US-6,084,297	07/04/2000	Brooks, J. M., et al.	257	698	09/03/1998
JP	US-6,084,777	07/04/2000	Kalidas, N., et al.	361	707	04/23/1998
JP	US-6,130,478	10/10/2000	Dumoulin, A., et al.	257	728	04/18/1998
JP	US-6,222,246	04/24/2001	Mak, T. M., et al.	257	532	01/08/1999
JP	US-6,239,482	05/29/2001	Fillion, Raymond A., et al.	257	678	06/21/1999
JP	US-6,388,333	05/14/2002	Taniguchi, F., et al.	257	777	06/27/2000
JP	US-6,590,291	07/08/2003	Akagawa, M.	257	774	01/25/2001

FOREIGN PATENT DOCUMENTS						
Examiner Initials *	Foreign Document No	Publication Date	Name of Patentee or Applicant of cited Document	Class	Subclass	T ²
JP	EP-0149317	07/24/1985	Heeks, J. S., et al.	H05K	3/28	
JP	EP-0361825	04/04/1990	Misawa, H.	H01L	23/522	
JP	EP-0431205	06/12/1991	Schroeder, J. A.	H01L	23/498	
JP	JP-10-125721	05/15/1998	Chikako, H.	H01L	21/60	
JP	JP-11-204688	07/30/1999	Kenji, A.	H01L	23/12	
JP	JP-2000-243870	09/08/2000	Akira, K.	H01L	23/12	
JP	JP-2000-307005	11/02/2000	Yasushi, T.	H01L	21/82	

OTHER DOCUMENTS -- NON PATENT LITERATURE DOCUMENTS			
Examiner Initials *	Cite No ¹	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.	T ²
JP		CHEN, CHANG-LEE, et al., "Bond Wireless Multichip Packaging Technology for High-Speed Circuits", IEEE Transactions on Components, Hybrids, and Manufacturing Technology, 15, NY, US, (1992), 451-456	
JP		DAUM, W., et al., "Overlay High-Density Interconnect: A Chips-First Multichip Module Technology", IEEE Computer Society, 26, Long Beach, CA, US, (1993), 23-29	
JP		GDULA, MICHAEL, et al., "An Overlay Interconnect Technology for 1GHz. and Above MCMs", Proceedings of the Multi Chip Module Conference (MCMC), Santa Cruz, US, (1992), 171-174	

EXAMINER

Ginette Peralta

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Substitute Disclosure Statement Form (PTO-1449)
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